### MICROWAVE POWER GaAs FET

### Internally Matched Power GaAs FETs (X, Ku-Band)

#### **Features**

- High power
  - $P_{1dB} = 36.5 \text{ dBm}$  at 14.5 GHz to 15.0 GHz
- High gain
- G<sub>1dB</sub> = 5.5 dB at 14.5 GHz to 15.0 GHz
  Broad Band Internally Matched
- · Hermetically sealed package

### RF Performance Specifications ( $T_a = 25^{\circ} C$ )

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P <sub>1dB</sub>		dBm	35.5	36.5	_
Power Gain at 1dB Compression Point	G <sub>1dB</sub>	V <sub>DS</sub> = 9V f = 14.5 ~ 15.0 GHz	dB	4.5	5.5	_
Drain Current	I <sub>DS</sub>		Α	_	1.7	2.2
Power Added Efficiency	η <sub>add</sub>		%	_	21	-
Channel-Temperature Rise	$\Delta T_{ch}$	V <sub>DS</sub> X I <sub>DS</sub> X R <sub>th(c-c)</sub>	°C	_	-	70

### Electrical Characteristics (T<sub>a</sub> = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	V <sub>DS</sub> =3V I <sub>DS</sub> =2.0 A	mS	_	1200	-
Pinch-off Voltage	V <sub>GSoff</sub>	V <sub>DS</sub> =3V I <sub>DS</sub> =60mA	V	-2	-3.5	-5
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =3V V <sub>GS</sub> =0V	А	_	4.0	5.2
Gate to Source Breakdown Voltage	$V_{GSO}$	I <sub>GS</sub> =60 μA	V	-5	_	_
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to case	°C/W	_	2.9	3.5

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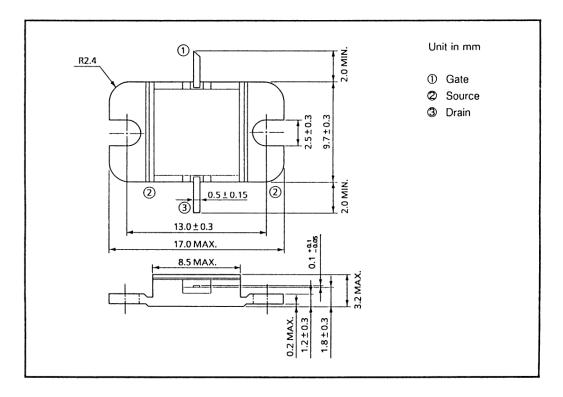
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The information contained here is subject to change without notice.

# Absolute Maximum Ratings ( $T_a = 25^{\circ} C$ )

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V <sub>DS</sub>	V	15
Gate Source Voltage	V <sub>GS</sub>	V	-5
Drain Current	I <sub>DS</sub>	А	5.2
Total Power Dissipation (Tc = 25°C)	P <sub>T</sub>	W	30
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65~175

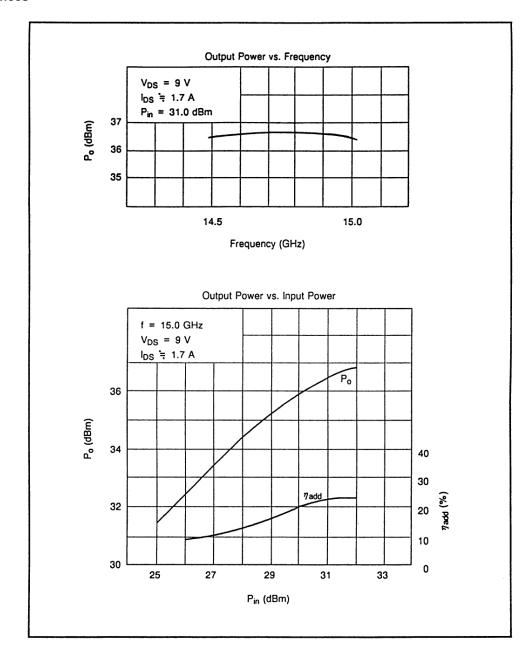
### Package Outline (2-9D1B)



### **Handling Precautions for Packaged Type**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

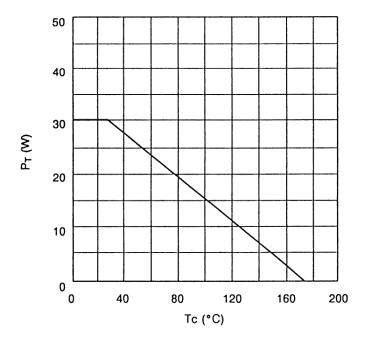
### **RF Performances**



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## **Power Dissipation vs. Case Temperature**



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